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(54) **METHOD FOR MANUFACTURING A SUBSTRATE FOR A RADIOFREQUENCY FILTER**

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(57) **ABSTRACT**

A method for manufacturing a substrate for a radiofrequency filter by joining a piezoelectric layer to a carrier substrate via an electrically insulating layer, wherein the method comprises depositing the electrically insulating layer by spin coating an oxide belonging to the family of SOGs (spin-on glasses) on the surface of the piezoelectric layer to be joined to the carrier substrate, followed by an anneal for densifying the electrically insulating layer before joining the piezoelectric layer to the carrier substrate via the electrically insulating layer.